



SOT1699-1

LQFP64, plastic, low profile quad flat package; 64 terminals;
0.5 mm pitch; 10 mm x 10 mm x 1.4 mm body

22 November 2019

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP64
Package style descriptive code	LQFP (low profile quad flat package)
Package body material type	P (plastic)
JEDEC package outline code	MS-026 BCD
Mounting method type	S (surface mount)
Issue date	25-01-2016
Manufacturer package code	98ASS23234W

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	9.8	10	10.2	mm
package width	9.8	10	10.2	mm
package height	1.35	1.4	1.45	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	64	-	



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2 Package outline

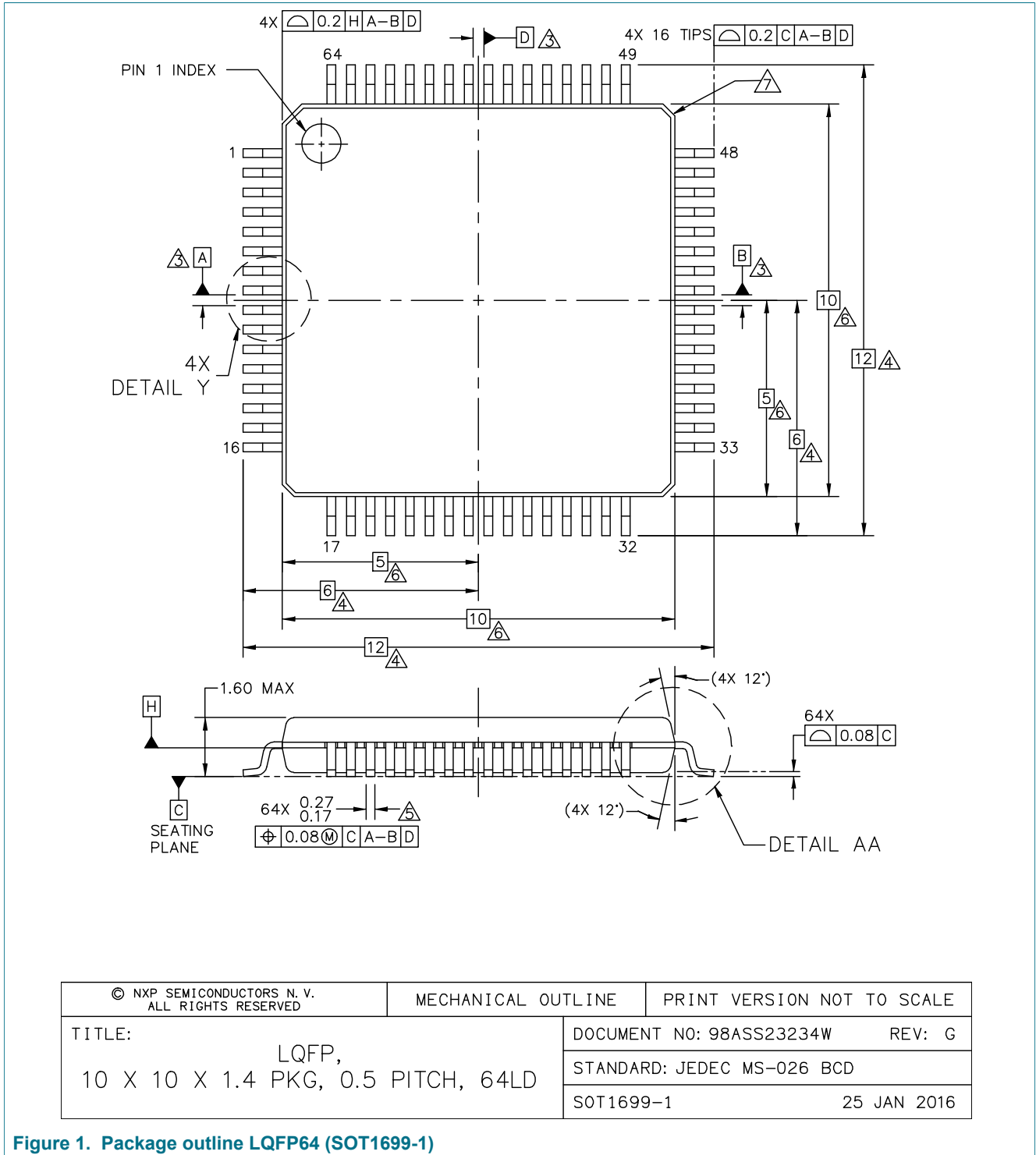


Figure 1. Package outline LQFP64 (SOT1699-1)

LQFP64, plastic, low profile quad flat package; 64 terminals; 0.5 mm pitch; 10 mm x 10 mm x 1.4 mm body

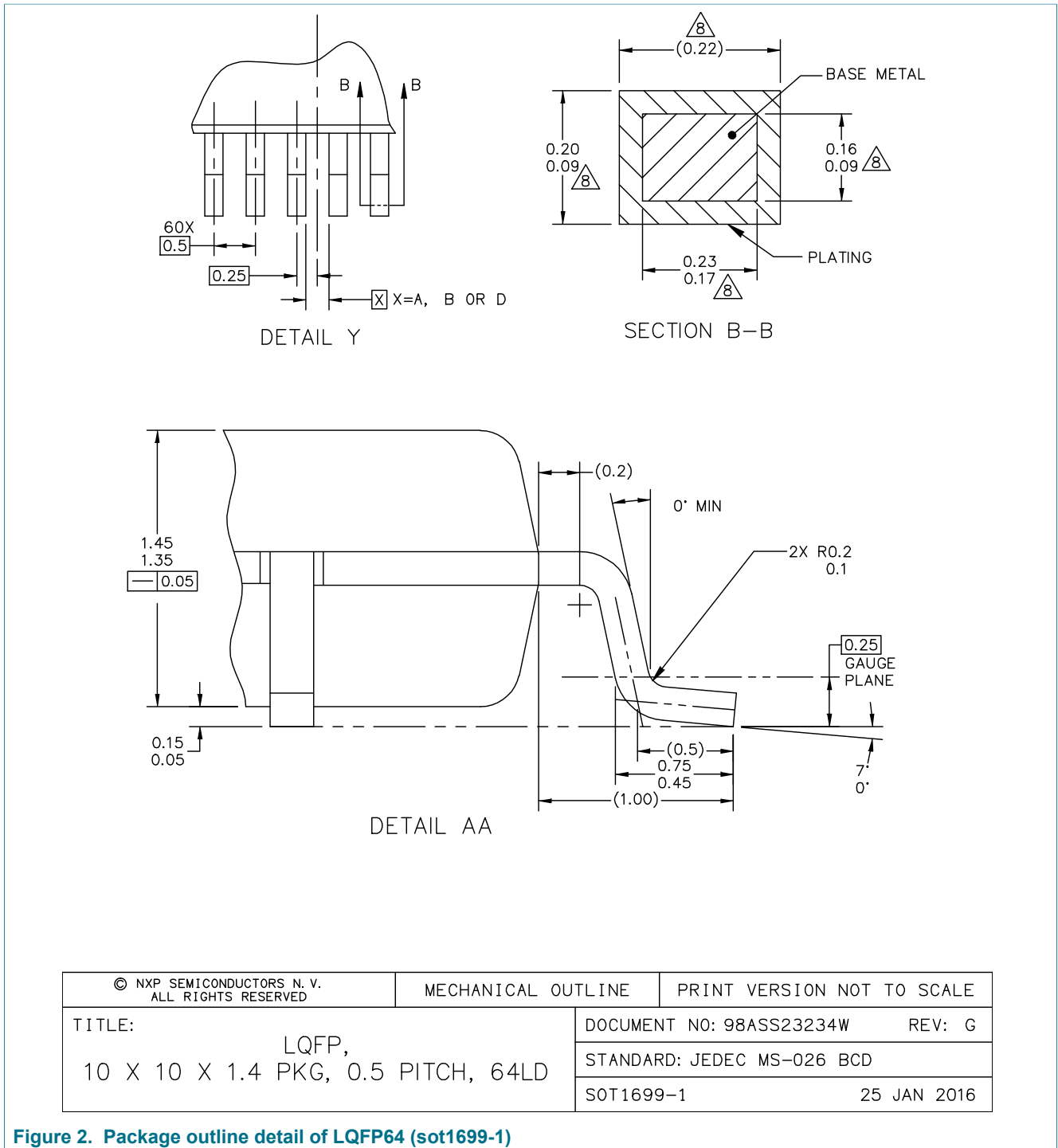


Figure 2. Package outline detail of LQFP64 (sot1699-1)

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NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
4. DIMENSIONS TO BE DETERMINED AT SEATING PLANE C.
5. THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08 MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07 MM.
6. THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25 MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
7. EXACT SHAPE OF EACH CORNER IS OPTIONAL.
8. THESE DIMENSIONS APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.1 MM AND 0.25 MM FROM THE LEAD TIP.

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TITLE: LQFP, 10 X 10 X 1.4 PKG, 0.5 PITCH, 64LD	DOCUMENT NO: 98ASS23234W	REV: G
	STANDARD: JEDEC MS-026 BCD	
	SOT1699-1	25 JAN 2016

Figure 3. Package outline note LQFP64 (sot1699-1)

3 Legal information

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body

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